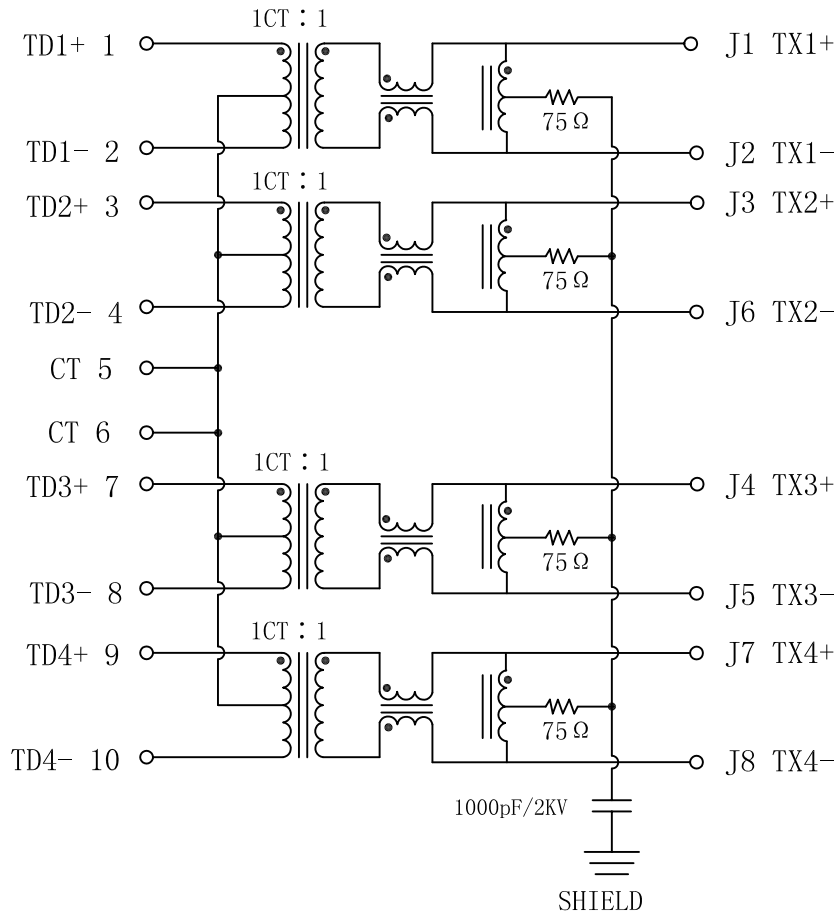


Schematic:

REV.	ECN NO.	DESCRIPTION	DATE	APPD
A	REL		17/12/2009	

PCB SIDE TO PHY

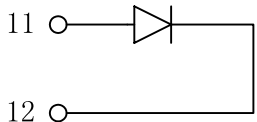


CABLE SIDE

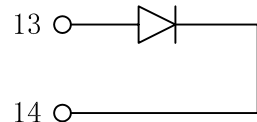
ELECTRICAL SPECIFICATIONS @25°C

- Turn Ratio ($\pm 2\%$):
TX=1CT:1 RX=1CT:1
- Inductance OCL: 350uH MIN
@100KHz, 0.1V, 8mA DC Bias
- Insertion Loss:
-1.2dB MAX @ 0.3-100MHz
- Return Loss:
-16dB MIN @ 1-30MHz
-13.5dB MIN @ 40MHz
-11.5dB MIN @ 50MHz
-10dB MIN @ 60-80MHz
- Cross talk:
-40dB MIN @ 30MHz
-36dB MIN @ 60MHz
-30dB MIN @ 100MHz
- Common Mode Rejection:
-35dB MIN @ 30MHz
-32dB MIN @ 60MHz
-30dB MIN @ 100MHz
- Hipot Test: 1500Vrms MIN
- Operating Temperature: 0°C TO 70°C.

GREEN/LEFT LED



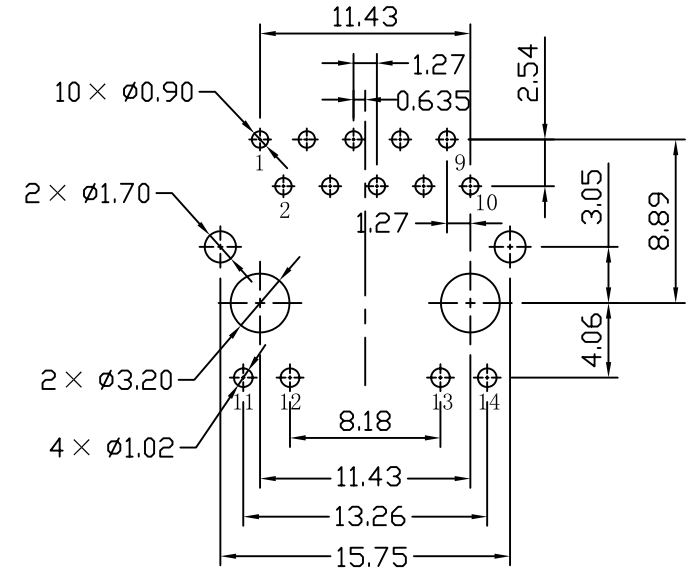
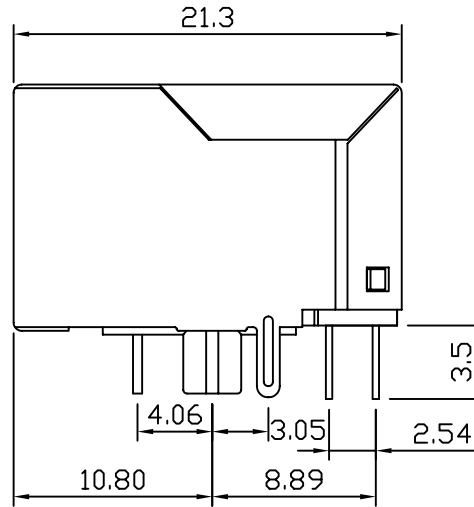
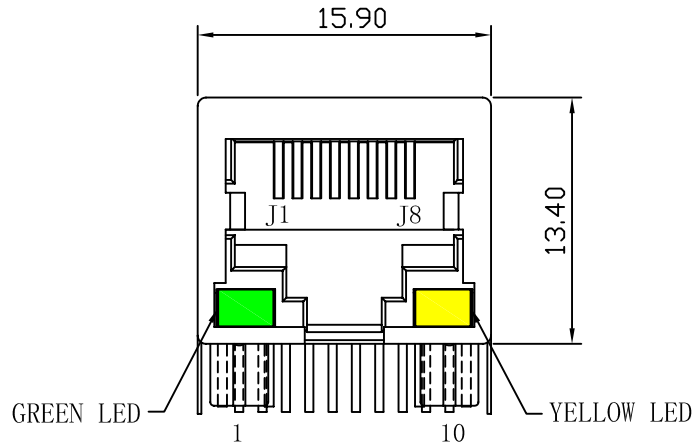
YELLOW/RIGHT LED



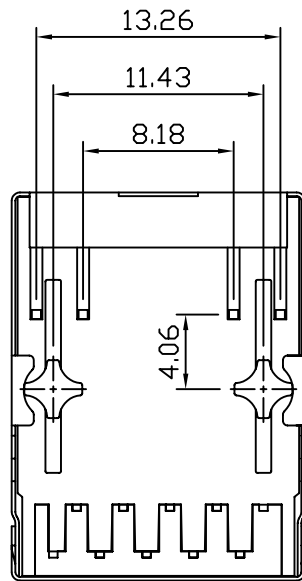
X:X ±0.30	APPD:	LINK-PP INT'L TECHNOLOGY CO., LIMITED		
X:XX ±0.20	CHKD:			
X:XXX ±0.05	DR: TOM	TITLE: RJ45 Connector with 1000 Base-T Integrated Magnetics		
ANGLES ±1°	UNIT: mm	PART NO.: LPJG0803HENL		
	SCALE: 2/1	SHEET: 1/2	REV: A	DWG NO.: LP09121706

Mechanical:

REV.	ECN NO.	DESCRIPTION	DATE	APPD
A	REL		17/12/2009	



SUGGESTED PCB LAYOUT (TOP VIEW)



NOTES:

1. Designed to support application, such as SOHO (ADSL modems), LAN-on-Motherboard (LOM), hub and Switches.
2. Meets IEEE 802.3 specification
3. Connector Materials:
 Housing: Thermoplastic UL94V-0
 Contact/Shield: Copper alloy
 Shield plating: Nickel
 Contact plating: Gold 6 micro-inches min. In contact area.
4. Wave solder tip temperature: 265°C Max
 Wave solder tip temperature time: 5 Sec Max



X:X ±0.30	APPD:	LINK-PP INT'L TECHNOLOGY CO., LIMITED
X:XX ±0.20	CHKD:	
X:XXX ±0.05	DR: TOM	
ANGLES ±1°	UNIT: mm	TITLE: RJ45 Connector with 1000 Base-T Integrated Magnetics
		PART NO.: LPJG0803HENL
	SCALE: 2/1	SHEET: 2/2
	REV: A	DWG NO.: LP09121706